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Date December 1, 2005
To Examiner Souw
Of USPTO
RE: 10/756,753
Fax 571-273-2482
From Dan Williams
Subject Proposed Claim amendments
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Pages 6
(including cover sheet)

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Examiner Souw,

Regarding 10/756,753 and further to our discussion on November 30, 2005, please find attached the set of amended claims including the changes that we discussed.

Thank you,

Dan Williams

APPENDIX

1. (currently amended): A thin film analyzing method for analyzing a constituent of a thin film, which comprises a cutting step of cutting the thin film obliquely and an analyzing step of analyzing the cut section of the thin film,

wherein the analyzing step is a step for measuring a distribution state of a specific component in the cut section of the thin film, and

wherein the distribution state of the specific component is analyzed by TOF-SIMS in the analyzing step.

2. (original): A thin film analyzing method according to claim 1, wherein the thin film is a thin film formed on a support.

3. (original): A thin film analyzing method according to claim 1, wherein the thin film has a multilayered structure.

4. (original): A thin film analyzing method according to claim 2, wherein the thin film is formed on a support and has a monolayered or multilayered structure.

5. (canceled).

6. (canceled).

7. (canceled).

8. (canceled).

9. (currently amended): A thin film analyzing method for analyzing a constituent of a thin film, which comprises a cutting step of cutting the thin film obliquely and an analyzing step of analyzing the cut section of the thin film,

wherein the analyzing step is a step for measuring a distribution state of a specific component in the cut section of the thin film, and

~~A thin film analyzing method according to claim 5,~~ wherein the distribution state of the specific component is analyzed by μ -ESCA in the analyzing step.

10. (canceled).

11. (original): A thin film analyzing method according to claim 1, wherein the thin film is cut with a microtome to which a cutting edge made of glass is fitted in the cutting step.

12. (original): A thin film analyzing method according to claim 4, wherein the thin film is cut with a microtome to which a cutting edge made of glass is fitted in the cutting step.

13. (original): A thin film analyzing method according to claim 11, wherein an edge angle of the cutting edge made of glass is 55° or less.

14. (original): A thin film analyzing method according to claim 12, wherein an edge angle of the cutting edge made of glass is 55° or less.

15. (original): A thin film analyzing method according to claim 1, wherein an angle for the cutting is set to 5° or less in the cutting step, thereby enlarging an area of the cut section in a film thickness direction 10 to 2800 times as compared with a case in which the thin film is cut perpendicularly to the surface of the thin film.

16. (original): A thin film analyzing method according to claim 4, wherein an angle for the cutting is set to 5° or less in the cutting step, thereby enlarging an area of the cut section in a film thickness direction 10 to 2800 times as compared with a case in which the thin film is cut perpendicularly to the surface of the thin film.

17. (original): A thin film analyzing method according to claim 1, wherein the thin film is a photosensitive thin film.

18. (original): A thin film analyzing method according to claim 17, wherein the photosensitive thin film is an image recording layer comprising a water-insoluble and alkali-soluble resin, an infrared ray absorber, and a colorant.

19. (original): A thin film analyzing method according to claim 1, wherein the thin film is a photosensitive thin film which is formed on a support and comprises a water-insoluble and

alkali-soluble resin, an infrared ray absorber, and a colorant, and in the analyzing step the distributions of the infrared ray absorber and the colorant in the thin film are analyzed.

20. (new): A thin film analyzing method according to claim 9, wherein the thin film is a thin film formed on a support.

21. (new): A thin film analyzing method according to claim 9, wherein the thin film has a multilayered structure.

22. (new): A thin film analyzing method according to claim 9, wherein the thin film is formed on a support and has a monolayered or multilayered structure.

23. (new): A thin film analyzing method according to claim 9, wherein the thin film is cut with a microtome to which a cutting edge made of glass is fitted in the cutting step.

24. (new): A thin film analyzing method according to claim 9, wherein the thin film is cut with a microtome to which a cutting edge made of glass is fitted in the cutting step.

25. (new): A thin film analyzing method according to claim 23, wherein an edge angle of the cutting edge made of glass is 55° or less.

26. (new): A thin film analyzing method according to claim 24, wherein an edge angle of the cutting edge made of glass is 55° or less.

27. (new): A thin film analyzing method according to claim 9, wherein an angle for the cutting is set to 5° or less in the cutting step, thereby enlarging an area of the cut section in a film thickness direction 10 to 2800 times as compared with a case in which the thin film is cut perpendicularly to the surface of the thin film.

28. (new): A thin film analyzing method according to claim 9, wherein an angle for the cutting is set to 5° or less in the cutting step, thereby enlarging an area of the cut section in a film thickness direction 10 to 2800 times as compared with a case in which the thin film is cut perpendicularly to the surface of the thin film.

29. (new): A thin film analyzing method according to claim 9, wherein the thin film is a photosensitive thin film.

30. (new): A thin film analyzing method according to claim 29, wherein the photosensitive thin film is an image recording layer comprising a water-insoluble and alkali-soluble resin, an infrared ray absorber, and a colorant.

31. (new): A thin film analyzing method according to claim 9, wherein the thin film is a photosensitive thin film which is formed on a support and comprises a water-insoluble and alkali-soluble resin, an infrared ray absorber, and a colorant, and in the analyzing step the distributions of the infrared ray absorber and the colorant in the thin film are analyzed.